SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520SECK08

Super Bright Orange

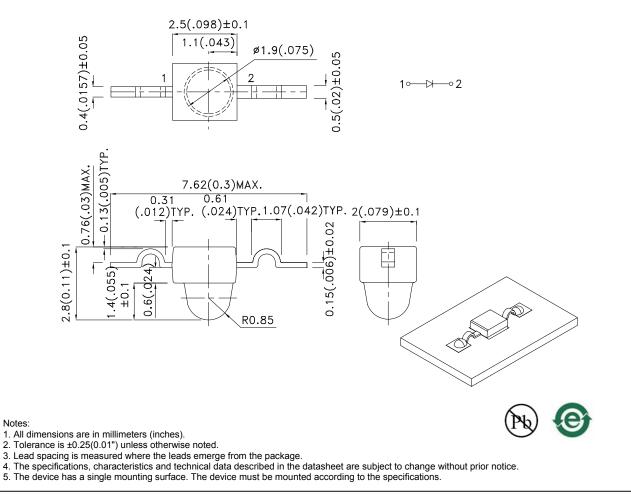
Features

- Subminiature package.
- Yoke lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

Description

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



SPEC NO: DSAD1269 APPROVED: WYNEC REV NO: V.5A CHECKED: Allen Liu DATE: APR/18/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1202000614

Solaction Guida

Selection Guide					
Part No.	Dice	Dice Lens Type Iv (mcd) [2] @ 20mA			Viewing Angle [1]
			Min.	Тур.	201/2
AM2520SECK08	Super Bright Orange (InCoAID)	Water Clear	1900	2700	20°
	Super Bright Orange (InGaAIP)	Water Cied	*1000	*1800	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	IF=20mA
lr	Reverse Current	Super Bright Orange		10	uA	Vr=5V

Notes:

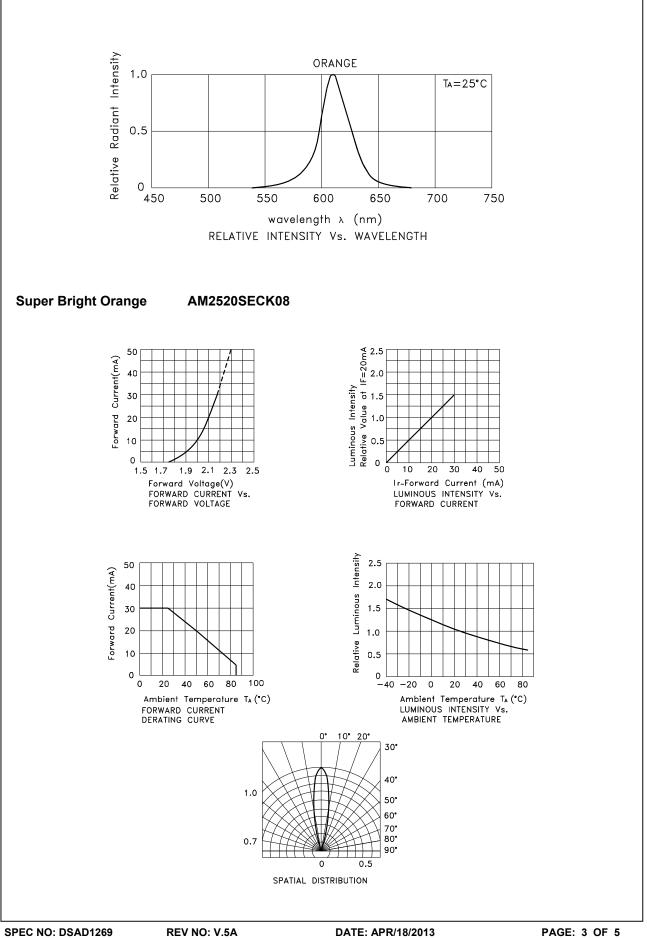
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V. 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Orange			
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	195	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note:

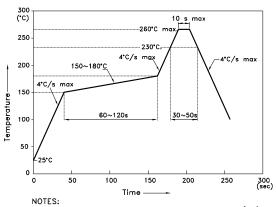
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



AM2520SECK08

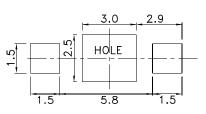
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

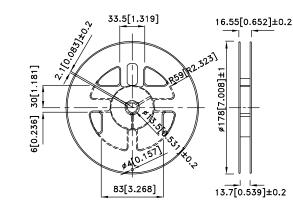


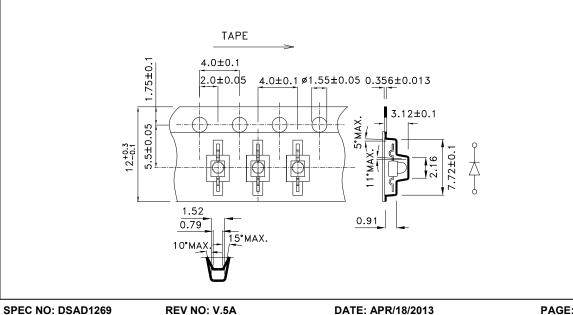
NOTES: 1.We recommend the reflow temperature $245^{\circ}C(+/-5^{\circ}C)$. The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)









Tape Dimensions

(Units : mm)

CHECKED: Allen Liu

DRAWN: F.Cui

